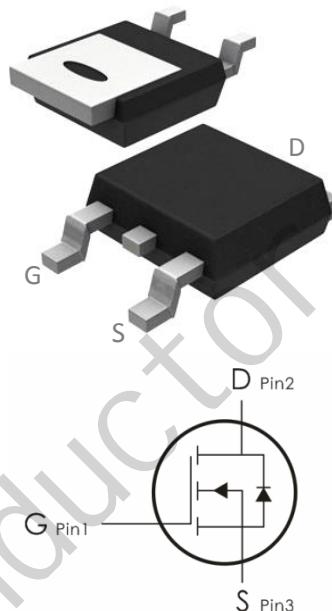


Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=150V, I_D=25A, R_{DS(ON)}<55m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	150	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D^*	Continuous Drain Current- $T_c=25^\circ C$	25	A
	Continuous Drain Current- $T_c=100^\circ C$	15	
	Pulsed Drain Current	76	
I_S	Continuous-Source Current	20	A
P_D	Power Dissipation	50	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\Theta JC}^{**}$	Thermal Resistance,Junction to Case	50	$^\circ C/W$
$R_{\Theta JA}^{**}$	Thermal Resistance,Junction to Ambient	2.5	

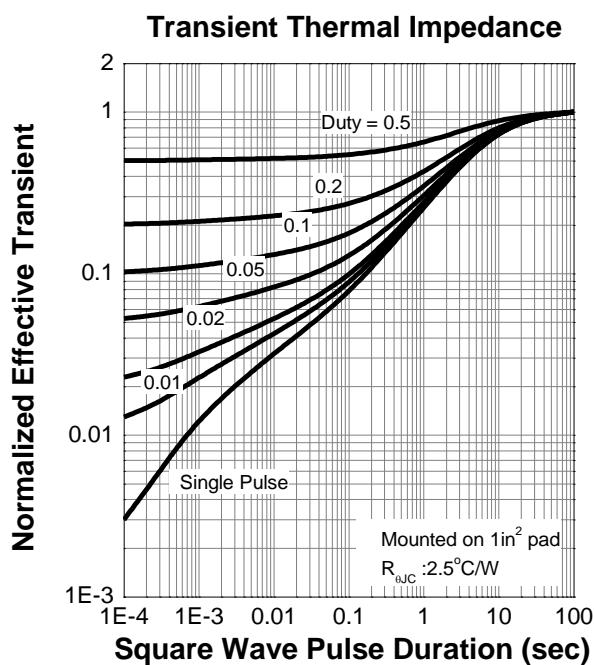
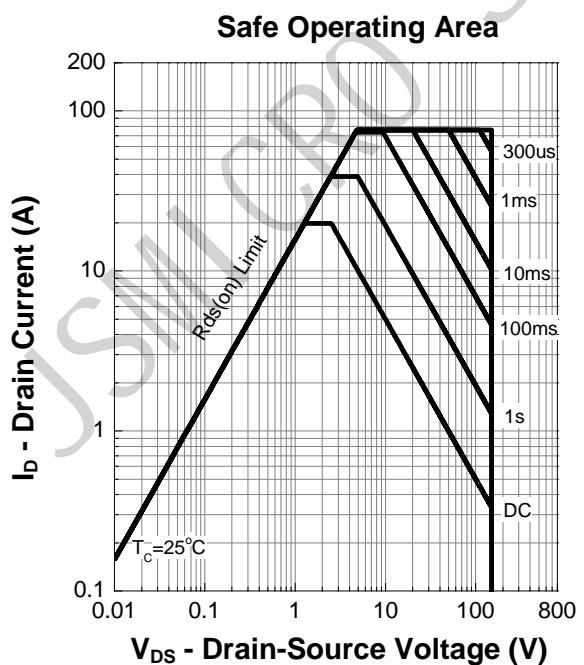
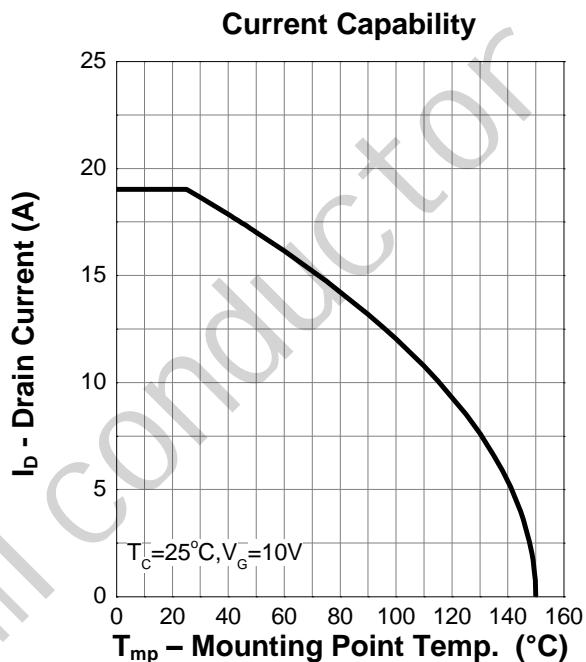
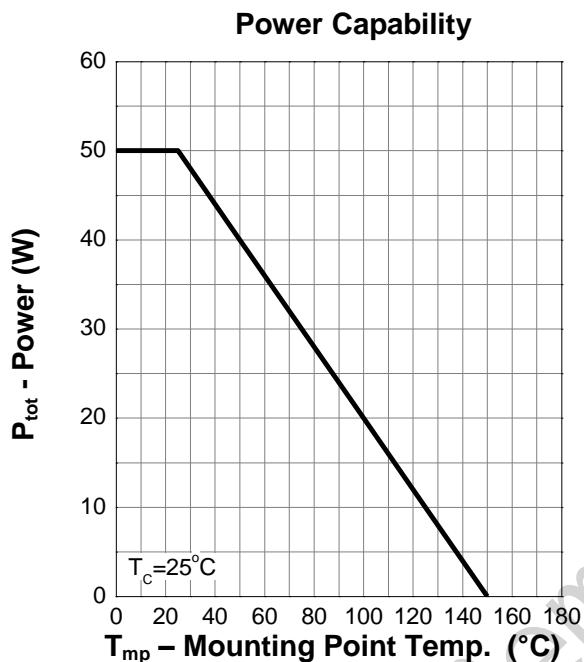
Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

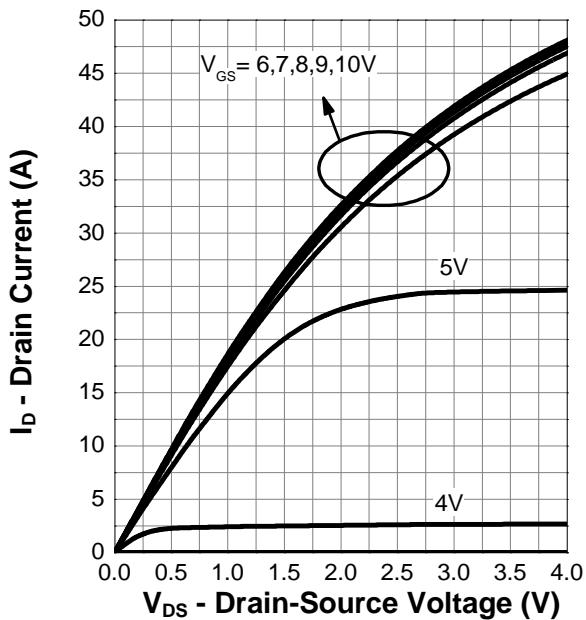
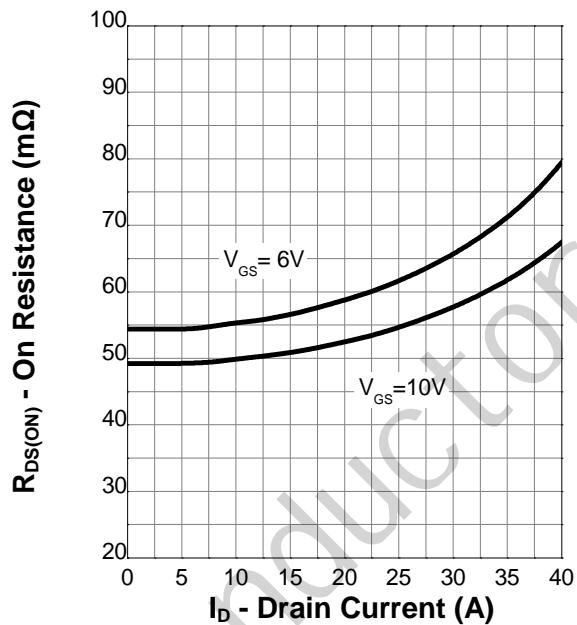
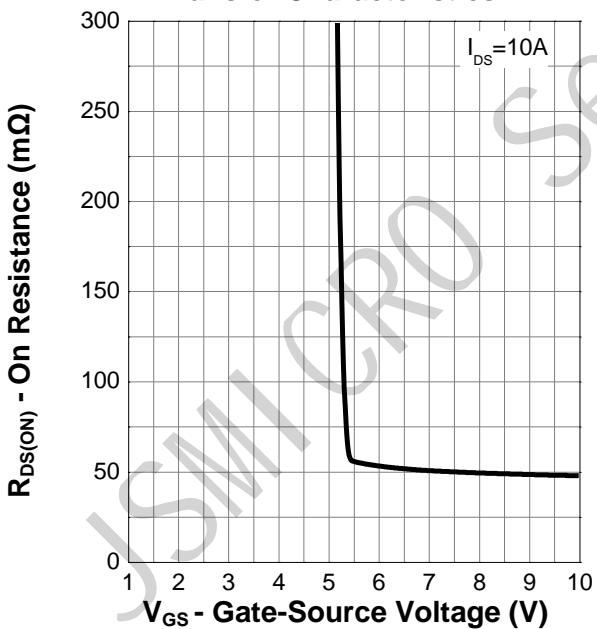
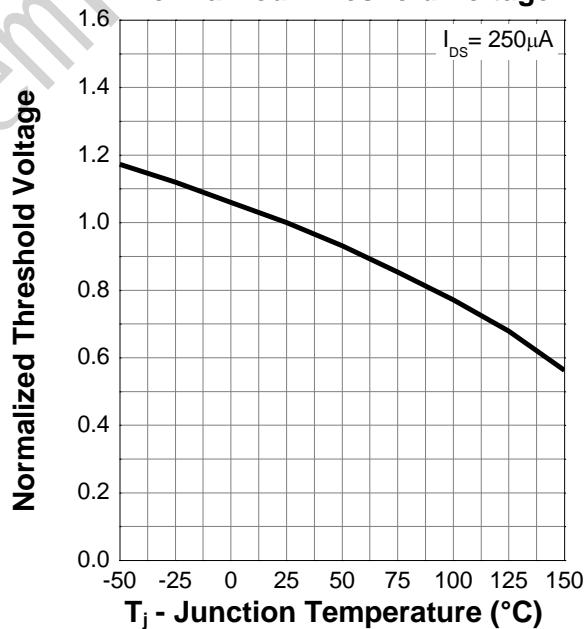
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=120\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 25\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	2	---	4	V
$R_{\text{DS}(\text{ON})}^{\text{a}}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	---	49	55	$\text{m}\Omega$
		$V_{\text{GS}}=6\text{V}, I_{\text{D}}=4\text{A}$	---	53	65	
Dynamic Characteristics^b						
C_{iss}	Input Capacitance	$V_{\text{DS}}=75\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1041	---	pF
C_{oss}	Output Capacitance		---	67	---	
C_{rss}	Reverse Transfer Capacitance		---	31	---	
Switching Characteristics^b						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=75\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=4.5\Omega, R_{\text{L}}=7.5\Omega$	---	9	--	ns
t_r	Rise Time		---	34	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	13.6	---	ns
t_f	Fall Time		---	36.8	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=75\text{V}, I_{\text{D}}=10\text{A}$	---	16.4	---	nC
Q_{gs}	Gate-Source Charge		---	6.2	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	2.7	---	nC
Drain-Source Diode Characteristics						
V_{SD}^{a}	Source-Drain Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=10\text{A}$	---	---	1.3	V
trr	Reverse Recovery Time	$I_{\text{DS}}=4\text{A}, V_{\text{GS}}=0\text{V}$	---	79	---	Ns
qrr	Reverse Recovery Charge	$dI_{\text{SD}}/dt = 100 \text{ A}/\mu\text{s}$		176	---	nc

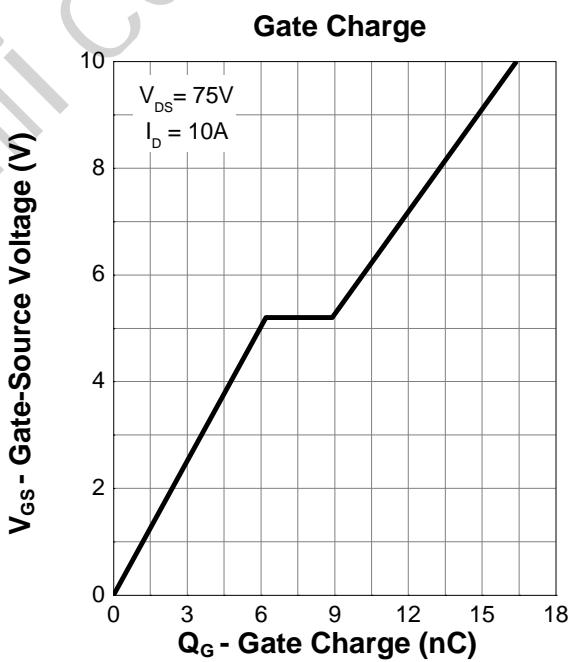
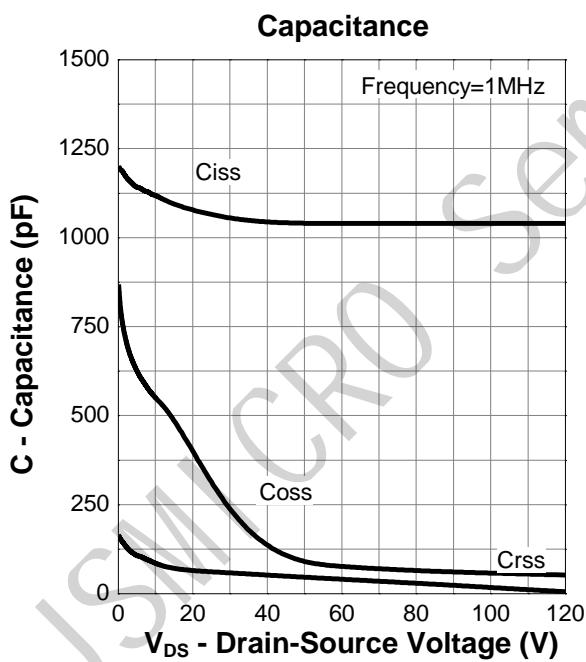
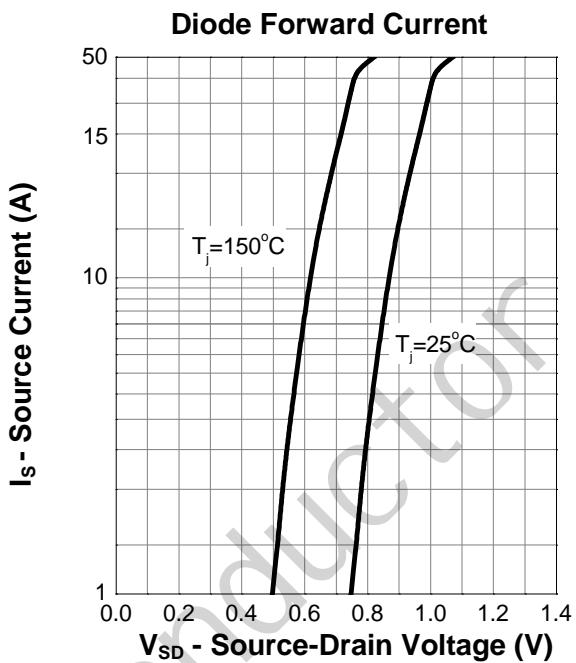
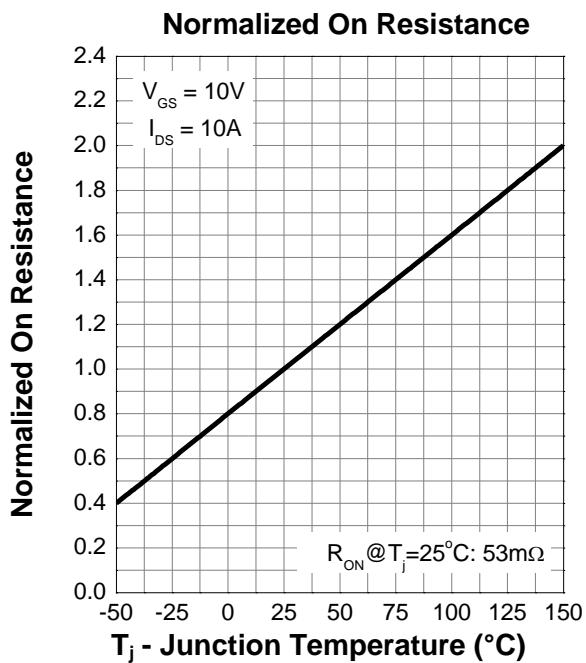
Notes:

- * Pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$
- ** Mounted on Large Heat Sink
- *** limited by bonding wire
- a : Pulse test ; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$
- b : Guaranteed by design, not subject to production testing

Typical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)



Output Characteristics

On Resistance

Transfer Characteristics

Normalized Threshold Voltage




外形尺寸图 / Package Dimensions

